

ABSTRACT OF THE DISCLOSURE

A DF formed of, for example, a photosensitive film is stacked on the electroconductive material and these portions, other than a projection electrode formation area, formed on a wiring board's electrode serving as a portion of a circuit pattern are masked with a mask. After this, the wiring board is exposed to light and, after the removal of the mask, a development process is performed, thus eliminating the DF on the wiring board at the portion other than the projection electrode formation area. Then the electroconductive material of the wiring board is etched under an etching process to provide a projection electrode having a bump with a pointed tapering end in vertical cross-section. Finally, the wiring board is exposed to a DF elimination solution to remove remaining DF from the projection electrode. And a plating process is performed on the electroconductive material to form a plated layer and hence complete the projection electrode.

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